

BRES24V0M2B3MAQ

Rev.B Apr.-2024



DATA SHEET

TVS Array in a SOT23 Plastic Package.

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/ Absolute Maximum Ratings(Ta=25)

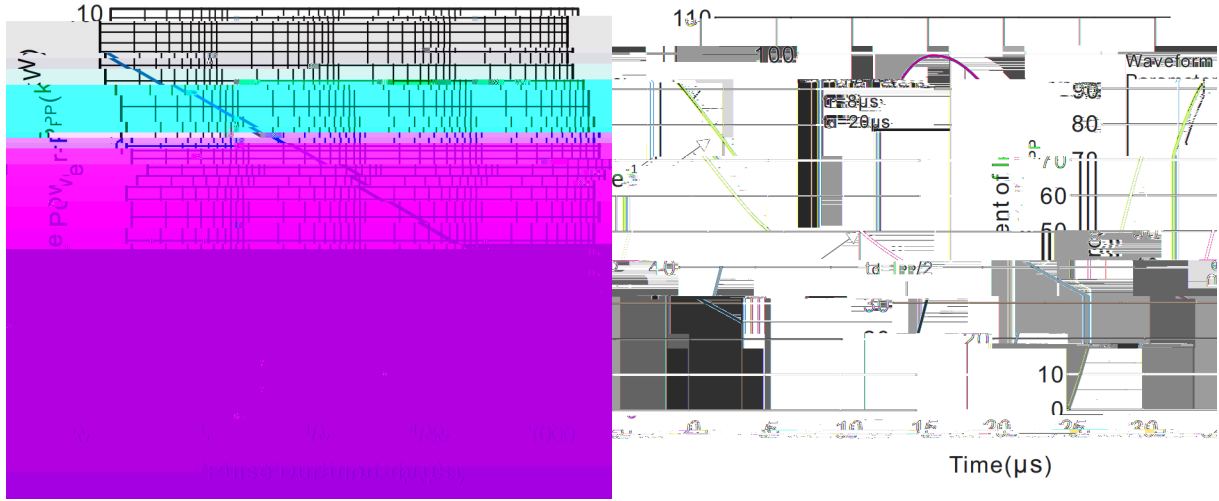
Parameter	Symbol	Rating	Unit
Peak Pulse Power (tp = 8/20 s)	P _{PP}	350	W
Peak Pulse Current (tp = 8/20 s)	I _{PP}	8.0	A
ESD per IEC 61000-4-2 (Air)	V _{ESD1}	±30	kV
ESD per IEC 61000-4-2 (Contact)	V _{ESD2}	±30	kV
Operating Temperature	T _{OPR}	-55 to +150	
Storage Temperature	T _{STG}	-55 to +150	

/ Electrical Characteristics(Ta=25)

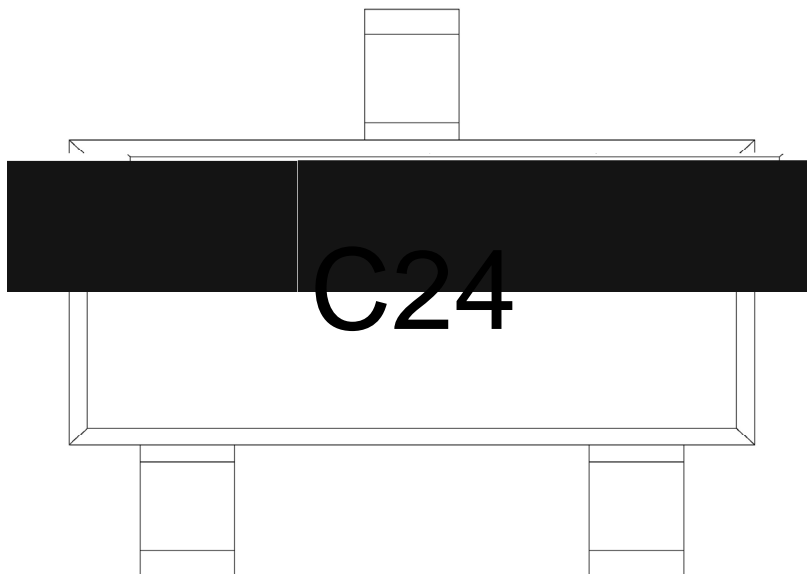
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V _{RWM}				24	V
Reverse Breakdown Voltage	V _{BR}	I _t =1mA	26.7			V
Reverse Leakage Current	I _R	V _{RWM} =24V T=25			1	A
Clamping Voltage	V _C	I _{PP} =1.0A t _p =8/20 S			33	V
	V _C	I _{PP} =8.0A t _p =8/20 S			44	V
Capacitance. Any I/O pin to GND	C _J	V _R =0V f=1MHz		25	30	pF

/ Electrical Characteristic Curve

Fig.1 Non-Repetitive Pulse Po2.H03(eZ.2r veZ.2s)-1.(. PulseT)18.(i)32.2me



/ Marking Instructions



Note:

C24: Product Type Code



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- 1 150 200 60 120sec; 1.Preheating:150~200 , Time:60~120sec.
- 2 255 5 5 0.5sec; 2.Peak Temp.:255 5 , Duration:5 0.5sec.
- 3 2 10 /sec. 3.Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec